



April 16, 2026

Henkel Taps Industry Experts for Webinar to Address Design Developments and Material Needs for Next-Gen AI

Irvine, California – Henkel announces that it will host a live technical webinar on May 19th and 20th tailored for semiconductor design engineers and manufacturers preparing for the next phase of AI scaling. The expert-led event will focus on the architectural and materials challenges impacting current and future AI devices, including performance and cost realities, the shift to chiplet adoption, changes to interposer designs, co-packaged optics considerations, and thermal management.

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Henkel Adhesive Technologies

INSIDE THE *FUTURE* OF AI AND **ADVANCED PACKAGING**

Join Henkel experts for a webinar on the technologies enabling next-gen AI and HPC systems.

Ram K. Trichur
Head of Market Strategy - Semiconductor Packaging
Henkel

Venky Sundaram
Founder & President
3D System Scaling LLC

SESSION 1 (US): 19TH MAY AT 10 AM PST

SESSION 2 (ASIA): 20TH MAY AT 10 AM SGT

REGISTER TODAY!

The webinar, entitled 'Advanced Packaging Developments Defining the Future of AI', will be led by Henkel's Head of Semiconductor Packaging, Ram Trichur, and will feature Venky Surendran, Founder of 3D System Scaling and a recognized expert in advanced semiconductor packaging. Together, Ram and Venky will present an in-depth technical briefing for semiconductor packaging designers, manufacturers, and integrators preparing for the new requirements of next-generation AI devices.

Among other topics, the webinar will cover:

- The evolution of AI architectures
- Interposer design comparisons and cost dynamics
- The role of co-packaged optics in AI scaling and the shift from 2D to 3D packaging
- Materials developments facilitating processing, protection, and thermal management of AI advanced packages

"AI design changes are happening fast," says Trichur, who highlights the accelerated shift from monolithic SoCs to chiplets in just the last few years as one example. "As a materials innovator working with some of today's top AI semiconductor packaging companies, Henkel has seen first-hand the thermal, mechanical, and processing complexity of emerging AI devices. This webinar will cover every aspect of these challenges – from how the trends shape practical design decisions to the material properties required to enable the continued evolution. Attendees will come away with a clear picture of what's coming and how to prepare -- it's an hour of time investment for some invaluable insight."

To learn more and secure a seat in one of the webinar sessions, visit this [registration page](#).

About Henkel

With its brands, innovations and technologies, Henkel holds leading market positions worldwide in the industrial and consumer businesses. The business unit Adhesive Technologies is the global leader in the market for adhesives, sealants and coatings. With Consumer Brands, the company holds leading positions especially in laundry & home care and hair in many markets and categories around the world. The company's three strongest brands are Loctite, Persil and Schwarzkopf. In fiscal 2025, Henkel reported sales of about 20.5 billion euros and adjusted operating profit of around 3.0 billion euros. Henkel's preferred shares are listed in the German stock index DAX. Sustainability has a long tradition at Henkel, and the company has a clear sustainability strategy with specific targets. Henkel was founded in 1876 and today employs a diverse team of about 47,000 people worldwide – united by a strong corporate culture, shared values and a common purpose: "Pioneers at heart for the good of generations." More information at www.henkel.com

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